

# Manufacturing Capabilites

		Standard	Advanced (Limited Qty)
Material Types	2 layers	FR-4, FR-4(180 Tg)	Teflon, Bt-Epoxy, Polyimide, Duriod Etc.
	4 Layers	FR-4, FR-4(180 Tg)	Teflon, Polyimide, Rogers, Arlon, Hybrids
Material Thickness	2 Layers	.010 - .125	.008 - .200"
	4 Layers	.031 - .125	.018 - .250"
	6 Layers	.047 - .125	.031 - .250"
	8 Layers	.062 - .125	.047 - .250"
Layer Count		1-10	12 +
Max Board Size	2 layer	16.00 X 22.00"	16.50" X 23.00"
	Multilayer	16.00 X 22.00"	16.00" X 22.50"
Copper Weight	Outer Layer	1 - 2 oz	3 - 8 oz
	Inner Layer	1 - 2 oz	3 - 6 oz
Trace / Space (min)	Outer Layer	.005" / .005"	.003" / .004"
	Inner Layer	.005" / .005"	.003" / .004"
PCB Edge to Conductor Min		.015"	.010"
Minimum Dielectric Thickness		.005"	.003"
Smallest Drilled Via		.0138"	.010"
Outer Via Pad Min.		.026"	.020"
Inner Via Pad Min.		.026"	.020"
Inner Layer Clearence Min.		.038"	.030"
PTH Tolerance Finished		+/- .003"	+/- .002"
Max Aspect Ratio		8:1	10:1
Plated Slots Min		.030"	.020"
Plated Features		Bumps, Edges, Countersinks / Bores, Pockets, Castellations	
Plated Countersinks (Deg.)		80, 90, 100	80, 90, 100
Surface Finishes		HASL, ENIG	HASL, ENIG, Pb Free HASL, Tin, Silver
Soldermask Color		Green, Blue, Black, Red	
Soldermask Dam (min)		.005"	.003"
Soldermask Clearence (min)		.004"	.002"
Legend Colors		White, Yellow, Black, Red, Blue	
Controlled Impedence + / -		10 %	10 %
SMT Pitch for Electrical Test		.012"	.008"
Bow & Twist		.75 %	.75 %
Min Rout Width		.062"	.031"
IPC Class		Class II	Class III